## **AMENDMENTS TO THE CLAIMS**

This Listing of Claims will replace all prior versions, listing, of claims in the specification.

## **LISTING OF CLAIMS:**

Claim 1 (original) An epitaxial structure of GaN based compound semiconductor comprising:

- a substrate;
- a single crystal of boron phosphide buffer layer on said substrate;
- a first buffer layer composed of group III nitride at a temperature from 200 to 800 degree C formed on said boron phosphide buffer layer; and
- a second buffer layer composed of group III nitride at a temperature from 800 to 1100 degree C formed on said first buffer layer.

Claim 2 (original) The epitaxial structure of GaN based compound semiconductor of claim 1, wherein said substrate is a single crystal silicon.

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Claim 3 (original) The epitaxial structure of GaN based compound semiconductor of claim 1, wherein said boron phosphide buffer layer comprises a first layer formed at a temperature from 300 to 850 degree C and a second layer formed at a temperature from 800 to 1100 degree C.

Claim 4 (original) The epitaxial structure of GaN based compound semiconductor of claim 1, wherein said first and second buffer layer are composed of  $Al_xIn_yGa_zN$ , wherein  $0 \le x \le 1$ ,  $0 \le y \le 1$ ,  $0 \le z \le 1$ , x+y+z=1.

Claim 5 (original) The epitaxial structure of GaN based compound semiconductor of claim 1, wherein said first and second buffer layer are composed of  $In_xGa_yN_zP$ , wherein  $0 \le x \le 1$ ,  $0 \le y \le 1$ ,  $0 \le z \le 1$ , x+y+z=1.

Claims 6-10 (canceled).